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U.S. Serial No. 09/982,347
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This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

Claims 1-7 (canceled)

Claim 8 (currently amended): A semiconductor package, comprising:

a substrate mounted with at least one semiconductor chip thereon and electrically connected to the semiconductor chip; and

an encapsulant formed by a molding compound injected into a molding cavity of a mold for encapsulating the semiconductor chip mounted on the substrate, wherein the molding cavity is formed with a plurality of recess portions at corner positions thereof, which and the recessed portions are dimensioned to be relatively smaller in height than the molding cavity[.], and the ~~recess portions~~ are each connected to an air vent formed in the mold for interconnecting the recess portions and outside of the mold, such that the encapsulant is formed with a plurality of outwardly-extending portions by the molding compound filled in the recess portions of the molding cavity, and the outwardly-extending portions are located in positions corresponding to the corner positions of the molding cavity.

Claim 9 (original): The semiconductor package of claim 8, wherein the semiconductor package is a BGA (ball grid array) semiconductor package.

Claim 10 (original): The semiconductor package of claim 8, wherein the semiconductor package is a FCBGA (flip chip ball grid array) semiconductor package.

Claim 11 (original): The semiconductor package of claim 8, wherein the molding compound is an epoxy resin having low viscosity, high fluidity and small fine filler size.

Claim 12 (original): The semiconductor package of claim 8, wherein a molded underfilling technique is employed for injecting the molding compound.